

VIGON® A 200

Water-based cleaning medium for flux removal



VIGON® A 200 is a water-based cleaning medium specifically developed for the use in high and medium spray pressure equipment such as inline or batch equipment. Based on MPC® Technology, VIGON® A 200 removes all types of flux residues from electronic assemblies, ceramic hybrids, power modules and lead frames. VIGON® A 200 meets the highest cleanliness requirements for subsequent wire bonding and coating steps.

Areas of application: PCB's, ceramic hybrids, power modules, lead frames		Additional product information:
Low solid flux residues*	++	Technical Information 2: Overview of all fluxes and solder pastes tested Technical Information 3: Material compatibility overview Application Recommendation: Specific process parameters for your cleaning trial MPC® Technology Information sheet: Additional information on MPC® Technology
Rosin-based flux residues*	++	
Water soluble flux residues*	++	
Solder pastes (unsoldered)	++	
SMT-adhesives or conductive adhesives	0	

++ highly recommended, best results + recommended 0 possible - not recommended
 * Valid for all standard-, lead-free and lead-based solders

Technical Centers - ① America, ② Europe, ③ Malaysia, ④ North-China, ⑤ South-China Cleaning Process Solutions under Production Floor Conditions



Advantages compared to other cleaners:

- VIGON® A 200 can easily be filtered and therefore provides an extended bath life and reduces cleaning agent costs.
- Due to its surfactant-free formulation, VIGON® A 200 can be easily rinsed and does not leave any residues on the surface.
- VIGON® A 200 has no flash point and thus can be applied in all spray-in-air equipment without explosion proof.
- VIGON® A 200 ensures highest cleanliness levels for subsequent wire bonding and coating steps.
- Does not contain any halogenated compounds.
- Does not foam, even in high pressure applications.
- Low odor.





Please refer to the material compatibility list (Technical Information 3) before cleaning plastics.

VIGON® A 200 is approved by leading international cleaning equipment manufacturers. Written approvals can be obtained from ZESTRON.

Process Steps	1. Cleaning	2. Rinsing	3. Drying
Spray-in-air (Inline and batch process)	VIGON® A 200	DI-water	Hot or circulated air

Technical Data		
Please note that the information below represents VIGON® A 200 at 20 % concentration.		
Density	(g/ccm) at 20°C/68°F	0.99
Surface tension	(mN/m) at 25°C/77°F	28.7
Boiling range	°C/°F	100 - 212 / 212 - 414
Flash point	°C/°F	None
pH-value	10g/l H ₂ O	10.9
Vapor pressure	(mbar) at 20°C/68°F	20
Cleaning temperature	°C/°F	40 – 60 / 104 – 140
Solubility in water		Soluble
Application concentration ¹	Concentrate in %	15 - 30
HMIS Rating	Health-Flammability-Reactivity	0 – 0 – 0

¹ VIGON® A 200 is recommended to be diluted with DI-water only.

PRODUCT FEATURES	
 Extensively tested and suitable for cleaning of lead-free solder pastes	 MPC® Technology ensures an extremely long bath life when used in a closed loop system
 100% compliance with EU guidelines (RoHS 1 & 2, WEEE)	 Product is free of any critical substances according to SIN & SVHC lists

Filter recommendation:

- To take full advantage of the MPC® Technology and further expand the bath life of VIGON® A 200, filtration is recommended.
- For details, please request our “Filter Recommendation” sheet.

Environmental, health and safety regulations:

- VIGON® A 200 is water-based and biodegradable.
- The cleaning agent is formulated free of any halogenated compounds and is environmentally friendly.
- Refer to the MSDS for specific handling precautions and instructions.

Availability/Storage:

- VIGON® A 200 is available as concentrate in 1l bottles, 5l or 25l containers and 200l drums.
- Store VIGON® A 200 in the original container at a temperature between 5 - 30°C / 41 - 86°F.
- The product has a minimum shelf life of 5 years in factory sealed containers.

Cleaning standards:

Electronic assemblies cleaned with VIGON® A 200 in a ZESTRON specified process meet the following industry standards:

- IPC-A-610 Visual cleanliness
- J-STD 001 Ionic and resin cleanliness
- IPC-TM 650 and DIN 32513 (surface resistance)
- J-STD 003 Solderability

Alternative product recommendation:

- For water-based defluxing of electronic assemblies in ultrasonic dip tanks, we recommend VIGON® US or VIGON® A 250.